

ABSTRACT OF THE DISCLOSURE

SUBSTRATE PROCESSING APPARATUS AND STORAGE MEDIUM

5 A substrate processing system capable of reliably releasing a wafer without
damaging the wafer is disclosed. The substrate processing system 200 includes a top ring
31, a vacuum forming mechanism 220, and a controller 5. A program causes a processor
5b to measure a height of the top ring 31, to compare the height of the top ring 31 with a
suction start position, and to form a vacuum inside an elastic bag 46 based on a result of
10 comparison between the height of the top ring 31 and the suction start position.

FIG. 6